

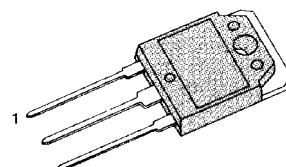
# SGH15N60RUF

CO-PAK IGBT

## FEATURES

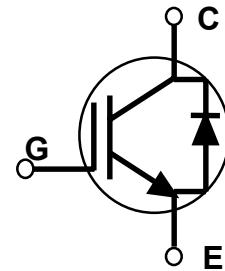
- \* Short Circuit rated 10uS @Tc=100 °C
- \* High Speed Switching
- \* Low Saturation Voltage  
:  $V_{CE}(\text{sat}) = 2.0 \text{ V}$  @  $I_c = 15\text{A}$
- \* High Input Impedance
- \* CO-PAK, IGBT with FRD  
:  $\text{Tr}_r = 42\text{nS}$  (Typ)

TO-3P



## APPLICATIONS

- \* AC & DC Motor controls
- \* General Purpose Inverters
- \* Robotics , Servo Controls
- \* Power Supply
- \* Lamp Ballast



## ABSOLUTE MAXIMUM RATINGS

Symbol	Characteristics	Rating	Units
$V_{CES}$	Collector-Emitter Voltage	600	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$I_c$	Collector Current @ $T_c = 25^\circ\text{C}$	24	A
	Collector Current @ $T_c = 100^\circ\text{C}$	15	A
$I_{CM(1)}$	Pulsed Collector Current	45	A
$I_F$	Diode Continuous Forward Current @ $T_c = 100^\circ\text{C}$	15	A
$I_{FM}$	Diode Maximum Forward Current	160	A
$P_D$	Maximum Power Dissipation @ $T_c = 25^\circ\text{C}$	160	W
	Maximum Power Dissipation @ $T_c = 100^\circ\text{C}$	64	W
$T_{sc}$	Short Circuit Withstand Time	10	$\mu\text{s}$
$T_j$	Operating Junction Temperature	-55 ~ 150	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range	-55 ~ 150	$^\circ\text{C}$
$T_L$	Maximum Lead Temp. For Soldering Purposes, $\frac{1}{8}''$ from case for 5 seconds	300	$^\circ\text{C}$

**Notes:** (1) Repetitive rating : Pulse width limited by max. junction temperature

**ELECTRICAL CHARACTERISTICS (IGBT PART)**  
 (T<sub>c</sub>=25°C, Unless Otherwise Specified)

Symbol	Characteristics	Test Conditions	Min	Typ	Max	Units
BV <sub>CES</sub>	C - E Breakdown Voltage	V <sub>GE</sub> = 0V , I <sub>C</sub> = 250µA	600	-	-	V
ΔV <sub>CES</sub> / ΔT <sub>J</sub>	Temperature Coeff. of Breakdown Voltage	V <sub>GE</sub> = 0V , I <sub>C</sub> = 1mA	-	0.6	-	V/°C
V <sub>GE(th)</sub>	G - E threshold voltage	I <sub>C</sub> = 15mA , V <sub>CE</sub> = V <sub>GE</sub>	5.0	6.0	8.0	V
I <sub>CES</sub>	Collector cutoff Current	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0V	-	-	250	uA
I <sub>GES</sub>	G - E leakage Current	V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0V	-	-	100	nA
V <sub>CE(sat)</sub>	Collector to Emitter saturation voltage	Ic=15A, V <sub>GE</sub> = 15V	-	2.0	2.7	V
		Ic=24A, V <sub>GE</sub> = 15V	-	2.4	-	V
Cies	Input capacitance	V <sub>GE</sub> = 0V , f = 1MHz V <sub>CE</sub> = 30V	-	937	-	pF
Coes	Output capacitance		-	157	-	pF
Cres	Reverse transfer capacitance		-	36	-	pF
td(on)	Turn on delay time	V <sub>CC</sub> = 300V , I <sub>C</sub> = 15A V <sub>GE</sub> = 15V R <sub>G</sub> = 13 Ω Inductive Load	-	70	-	nS
tr	Turn on rise time		-	20	-	nS
td(off)	Turn off delay time		-	60	90	nS
tf	Turn off fall time		-	70	140	nS
Eon	Turn on Switching Loss		-	0.1	-	mJ
Eoff	Turn off Switching Loss		-	0.3	-	mJ
Ets	Total Switching Loss		-	0.4	0.7	mJ
Tsc	Short Circuit withstand Time	V <sub>CC</sub> = 300V, V <sub>GE</sub> = 15V @T <sub>c</sub> = 100°C	10	-	-	uS
Qg	Total Gate Charge	V <sub>CC</sub> = 300V V <sub>GE</sub> = 15V I <sub>C</sub> = 15A	-	64	96	nC
Qge	Gate-Emitter Charge		-	15	22	nC
Qgc	Gate-Collector Charge		-	21	31	nC

**ELECTRICAL CHARACTERISTICS (DIODE PART)**  
(T<sub>c</sub>=25°C, Unless Otherwise Specified)

Symbol	Characteristics	Test Conditions		Min	Typ	Max	Units	
VFM	Diode Forward Voltage	IF=15A	T <sub>c</sub> =25 °C	-	1.4	1.7	V	
			T <sub>c</sub> =100 °C	-	1.3	-		
Tr	Diode Reverse Recovery Time	IF=15A, VR=200V -di/dt=200A/uS	T <sub>c</sub> =25 °C	-	42	60	nS	
			T <sub>c</sub> =100 °C	-	74	-		
Irr	Diode Peak Reverse Recovery Current		T <sub>c</sub> =25 °C	-	4.0	6.0	A	
			T <sub>c</sub> =100 °C	-	6.5	-		
Qrr	Diode Reverse Recovery Charge		T <sub>c</sub> =25 °C	-	80	180	nC	
			T <sub>c</sub> =100 °C	-	220	-		

**THERMAL RESISTANCE**

Symbol	Characteristics	Min	Typ	Max	Units
R <sub>θ</sub> JC	Junction-to-Case (IGBT)	-	-	0.77	°C/W
R <sub>θ</sub> JC	Junction-to-Case (DIODE)	-	-	1.70	°C/W
R <sub>θ</sub> JA	Junction-to-Ambient	-	-	40	°C/W
R <sub>θ</sub> CS	Case-to-Sink	-	0.24	-	°C/W

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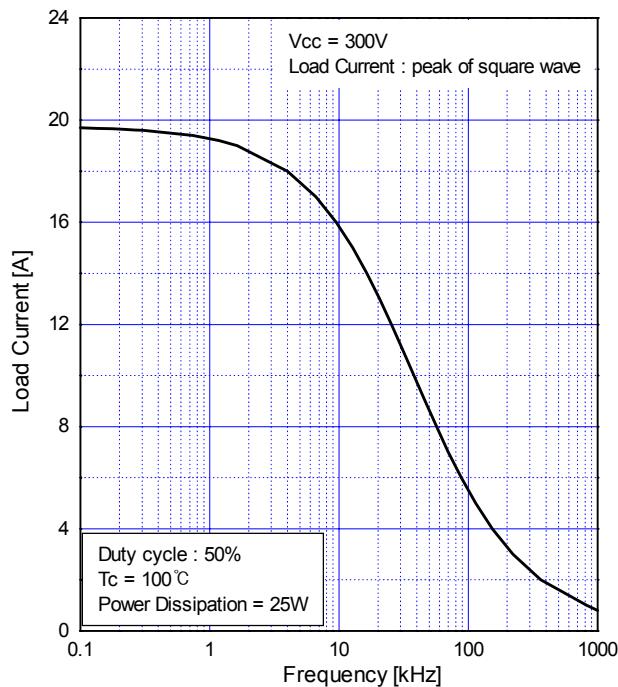


Fig.1 Typical Load Current vs. Frequency

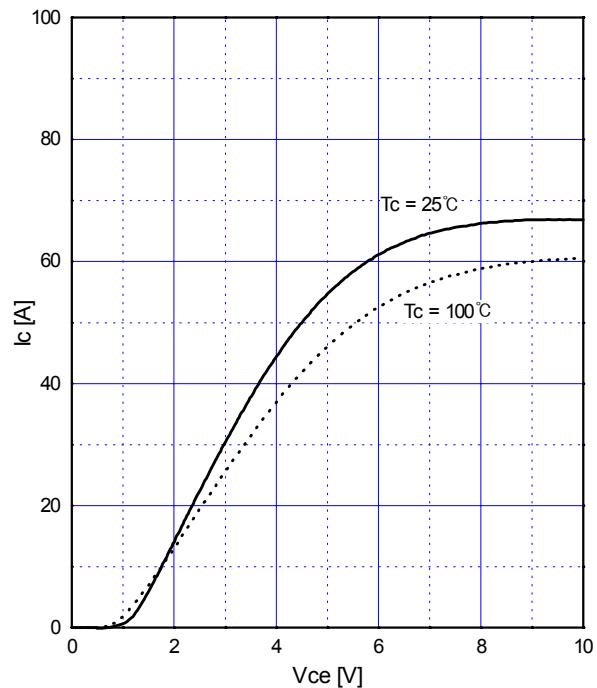


Fig.2 Typical Output Characteristics

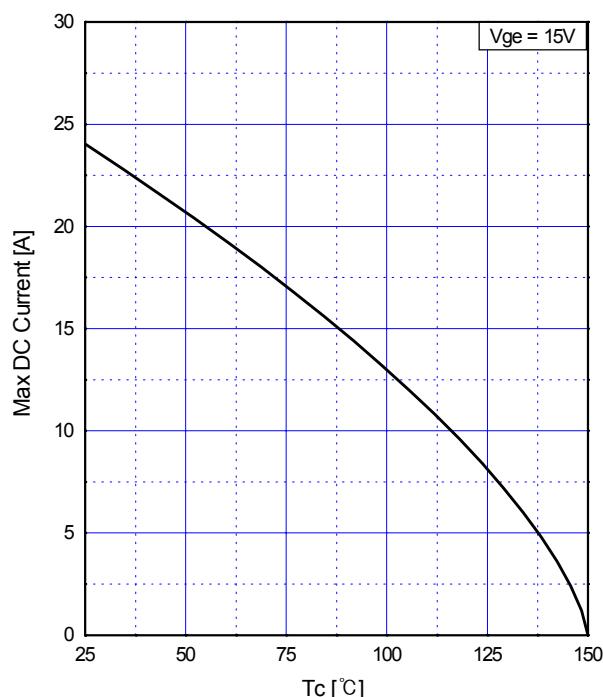


Fig.3 Maximum Collector Current vs. Case Temperature

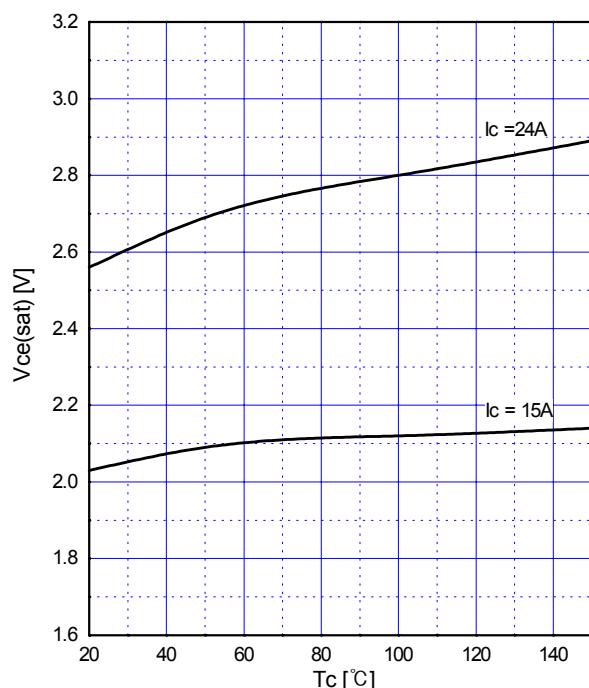


Fig.4 Collector to Emitter Voltage vs. Case Temperature

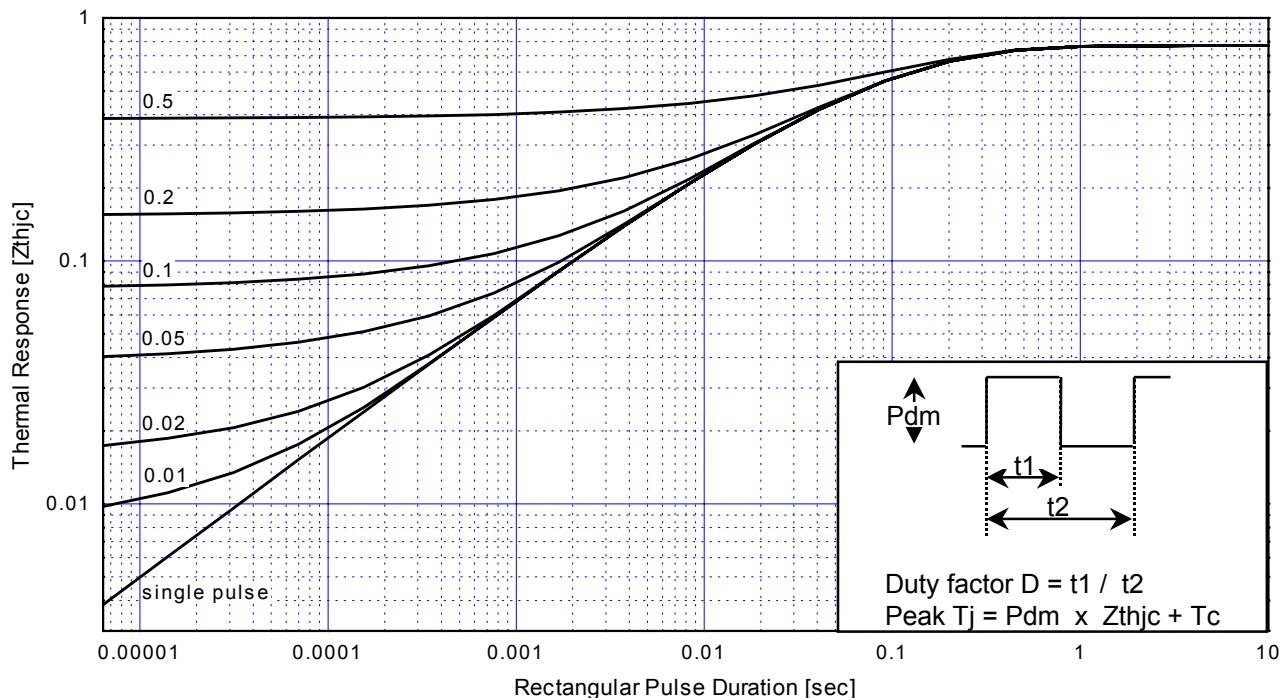


Fig.5 Maximum Effective Transient Thermal Impedance, Junction to Case

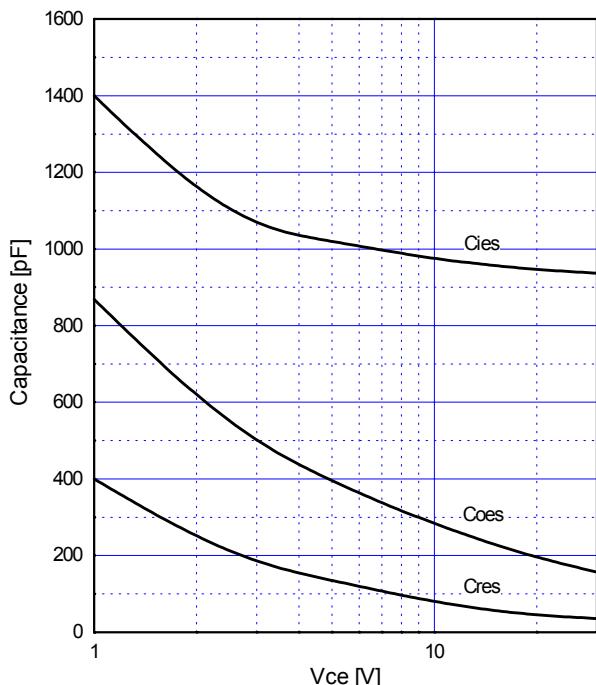


Fig.6 Typical Capacitance vs.  
Collector to Emitter Voltage

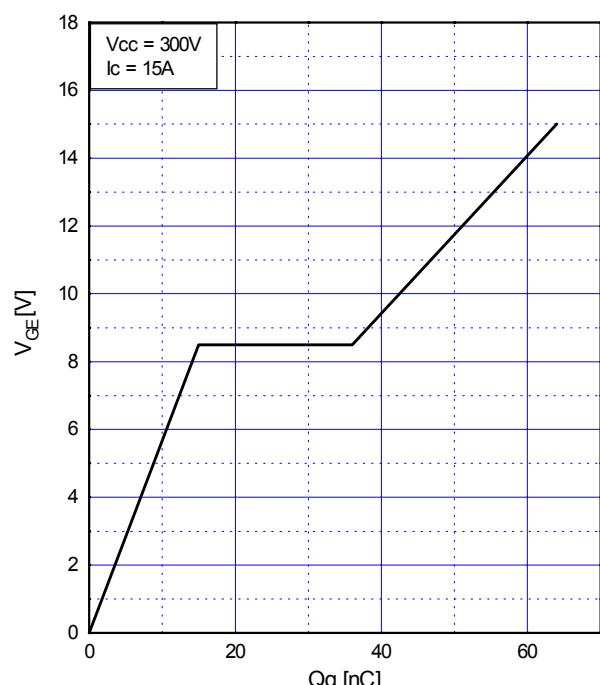


Fig.7 Typical Gate Charge vs.  
Gate to Emitter Voltage

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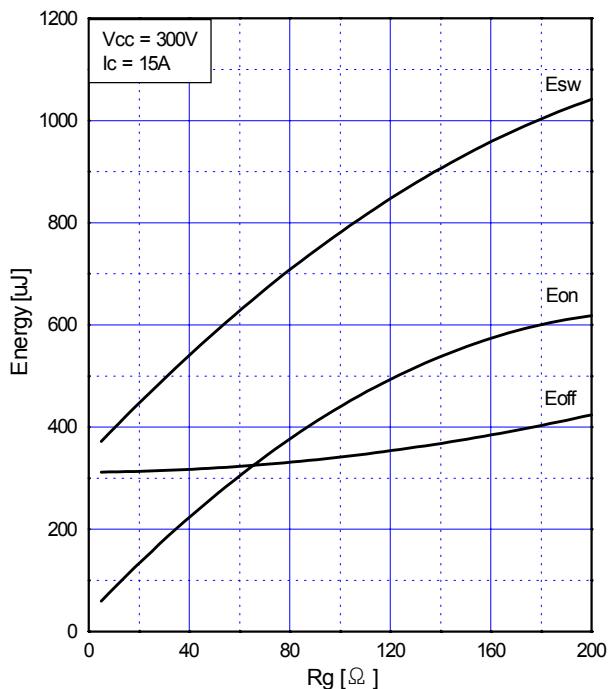


Fig.8 Typical Switching Loss vs.  
Gate Resistance

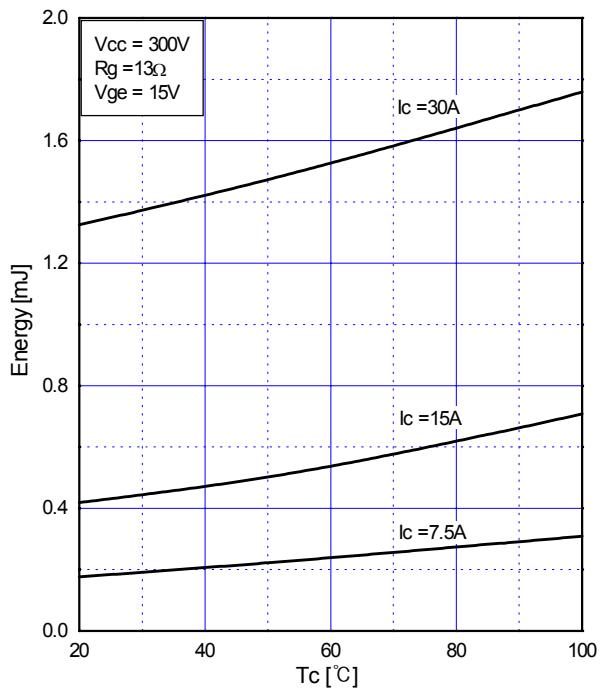


Fig.9 Typical Switching Loss vs.  
Case Temperature

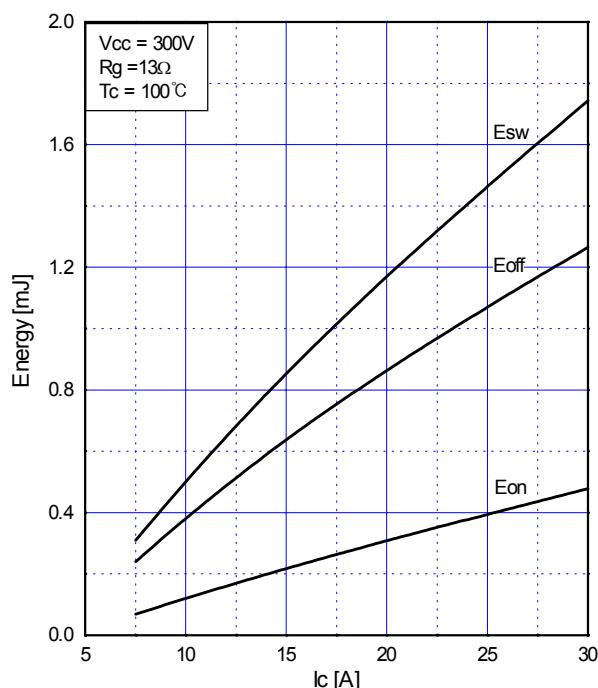


Fig.10 Typical Switching loss vs.  
Collector to Emitter Current

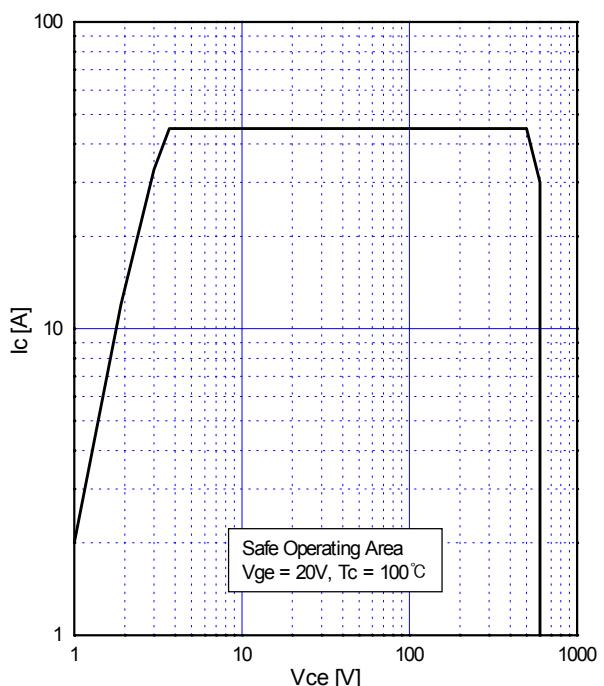


Fig.11 Turn-off SOA

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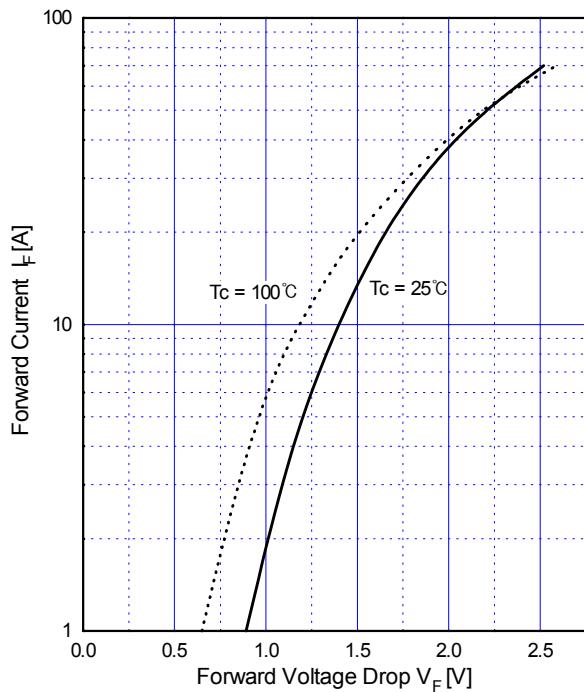


Fig.12 Typical Forward Voltage Drop  
vs. Forward Current

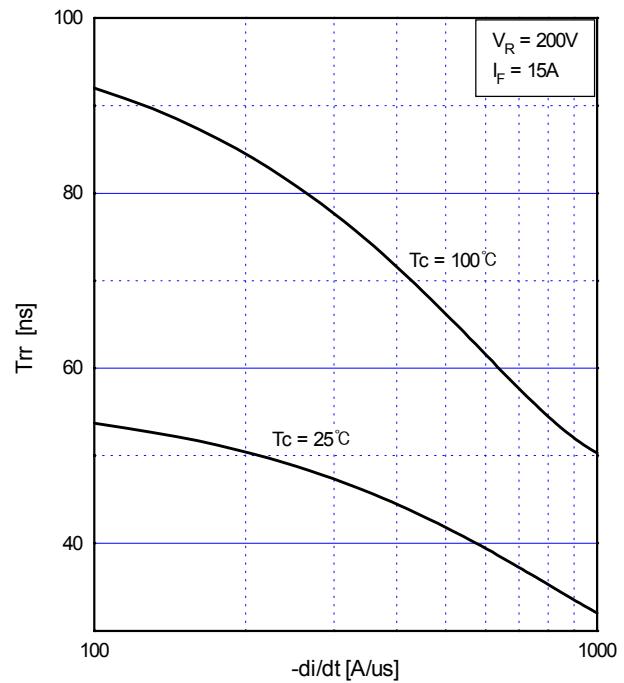


Fig.13 Typical Reverse Recovery Time  
vs.  $di/dt$

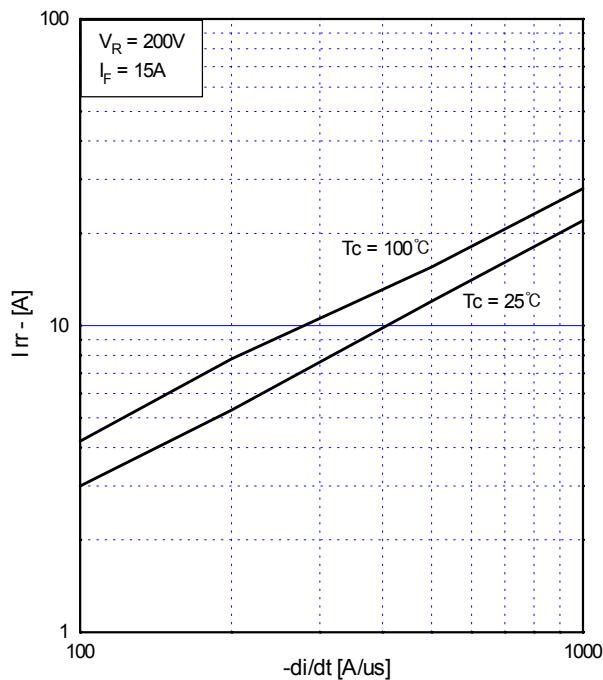


Fig.14 Typical Reverse Recovery Current  
vs.  $di/dt$

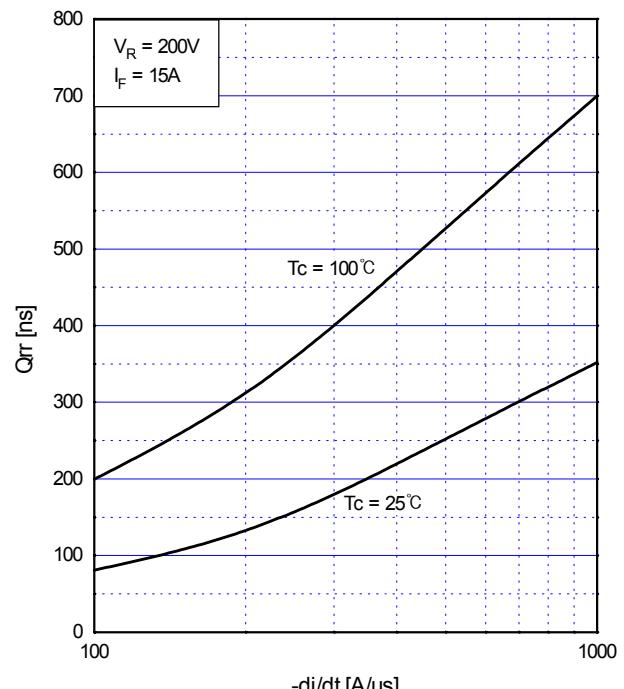


Fig.15 Typical Stored Charge vs.  $di/dt$